



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Shoji TSUZUKI

Application No.: 09/671,884

Filed: January 10, 2001

For: A CONNECTION SUBSTRATE, A METHOD OF MANUFACTURING THE CONNECTION SUBSTRATE, A SEMICONDUCTOR DEVICE, AND A METHOD OF MANUFACTURING THE SEMICONDUCTOR DEVICE

Group Art Unit: 2823

Examiner: B. Kebede

Docket No.: 107927

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AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed May 2, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claim 11 as follows:

11. (Amended) A method of manufacturing a semiconductor device, comprising:
- a step of forming a connection substrate on a base, comprising, forming a metal wire to be connected to an electrode formed on a semiconductor chip, on a first base, applying an insulating material onto the metal wire to form an insulation layer, and forming another metal wire on the insulation layer, thereby connecting the metal wires which sandwich the insulation layer, through a contact hole formed in the insulation layer;
 - a step of disposing a second base on the connection substrate;
 - a step of separating the first base from the connection substrate;